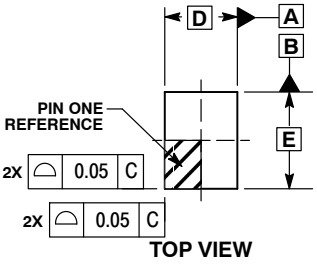
# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

ON Semiconductor®

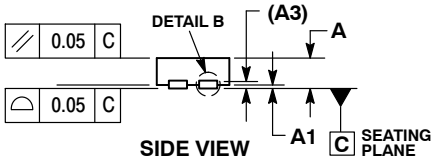
**UDFN4 1.2x1.6, 0.5P**
CASE 517CE
ISSUE B

DATE 03 APR 2012

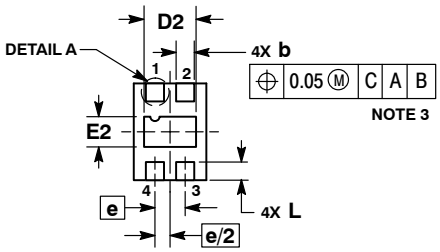
**SCALE 4:1**



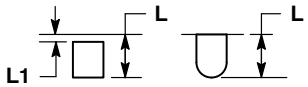

**TOP VIEW**



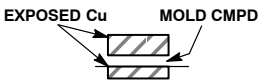

**SIDE VIEW**




**BOTTOM VIEW**




**DETAIL A**
**ALTERNATE TERMINAL CONSTRUCTIONS**




**DETAIL B**
**ALTERNATE CONSTRUCTION**

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

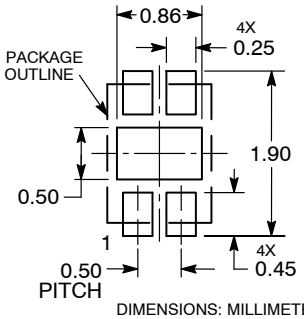
| | MILLIMETERS | | |
|---|---|---|---|
| DIM | MIN | NOM | MAX |
| A | 0.45 | 0.50 | 0.55 |
| A1 | 0.00 | --- | 0.05 |
| A3 | | 0.13 REF | |
| b | 0.25 | 0.30 | 0.35 |
| D | | 1.20 BSC | |
| D2 | 0.76 | 0.86 | 0.96 |
| E | | 1.60 BSC | |
| E2 | 0.40 | 0.50 | 0.60 |
| e | | 0.50 BSC | |
| L | 0.20 | 0.30 | 0.40 |
| L1 | --- | --- | 0.15 |

### GENERIC MARKING DIAGRAM*


XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

### RECOMMENDED MOUNTING FOOTPRINT*




DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| **DESCRIPTION:** | **UDFN4, 1.2X1.6, 0.5P** | **PAGE 1 OF 1** |